BC53PA series

80 V, 1 A PNP medium power transistors

Rev. 10 — 4 August 2023 Product data sheet

1. General description

PNP medium power transistors in an ultra thin SOT1061 leadless small Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- High current
- Three current gain selections
- High power dissipation capability
- Exposed heatsink for excellent thermal and electrical conductivity
- Leadless very small SMD plastic package with medium power capability
- AEC-Q101 qualified

3. Applications

- Linear voltage regulators
- High-side switches
- Battery-driven devices
- Power management
- MOSFET drivers
- Amplifiers

4. Quick reference data

Table 1. Quick reference data

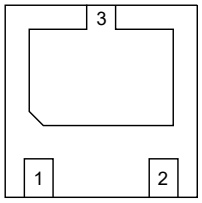
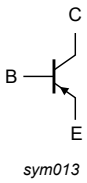
T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base		-	-	-80	V
I_C	collector current			-	-	-1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	-	-2	A
h_{FE}	DC current gain						
	BC53PA	V_{CE} = -2 V; I_C = -150 mA; T_{amb} = 25 °C	[1]	63	-	250	
	BC53-10PA		[1]	63	-	160	
	BC53-16PA		[1]	100	-	250	

[1] pulsed; $t_p \leq 300$ µs; $\delta \leq 0.02$

5. Pinning information

Table 2. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 Transparent top view	 sym013
2	E	emitter		
3	C	collector		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BC53PA	-	plastic, leadless thermal enhanced ultra thin small outline package ; no leads; 3 terminals; 2 mm x 2 mm x 0.65 mm body	SOT1061
BC53-10PA			
BC53-16PA			

7. Marking

Table 4. Marking

Type number	Marking code
BC53PA	BV
BC53-10PA	BW
BC53-16PA	BX

8. Limiting values

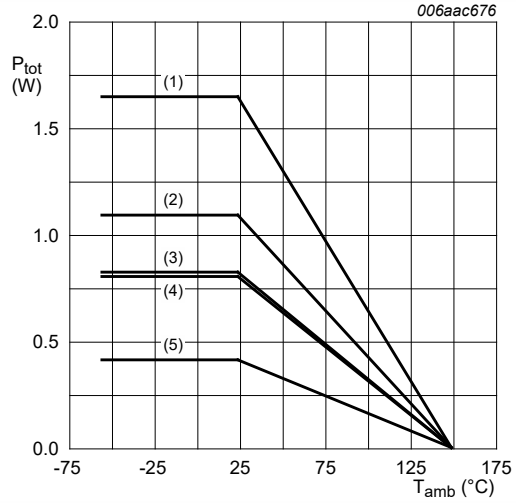
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	-100	V
V_{CEO}	collector-emitter voltage	open base		-	-80	V
V_{EBO}	emitter-base voltage	open collector		-	-5	V
I_C	collector current			-	-1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	-2	A
I_B	base current			-	-0.3	A
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms		-	-0.3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	0.42	W
			[2]	-	0.83	W
			[3]	-	1.10	W
			[4]	-	0.81	W
			[5]	-	1.65	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm^2.
[3] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm^2.
[4] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
[5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm^2.



(1) FR4 PCB, 4-layer copper, mounting pad for collector 1 cm^2
(2) FR4 PCB, single-sided copper, mounting pad for collector 6 cm^2
(3) FR4 PCB, single-sided copper, mounting pad for collector 1 cm^2
(4) FR4 PCB, 4-layer copper, standard footprint
(5) FR4 PCB, single-sided copper, standard footprint

Fig. 1. Power derating curves SOT1061

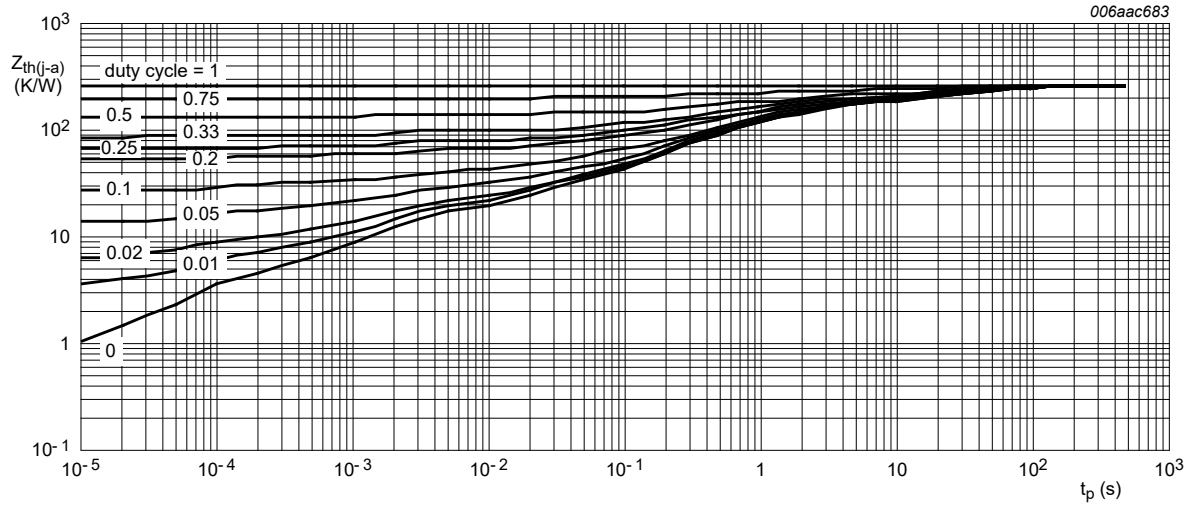
9. Thermal characteristics

Table 6. Thermal characteristics

T_{amb} = 25 °C unless otherwise specified.

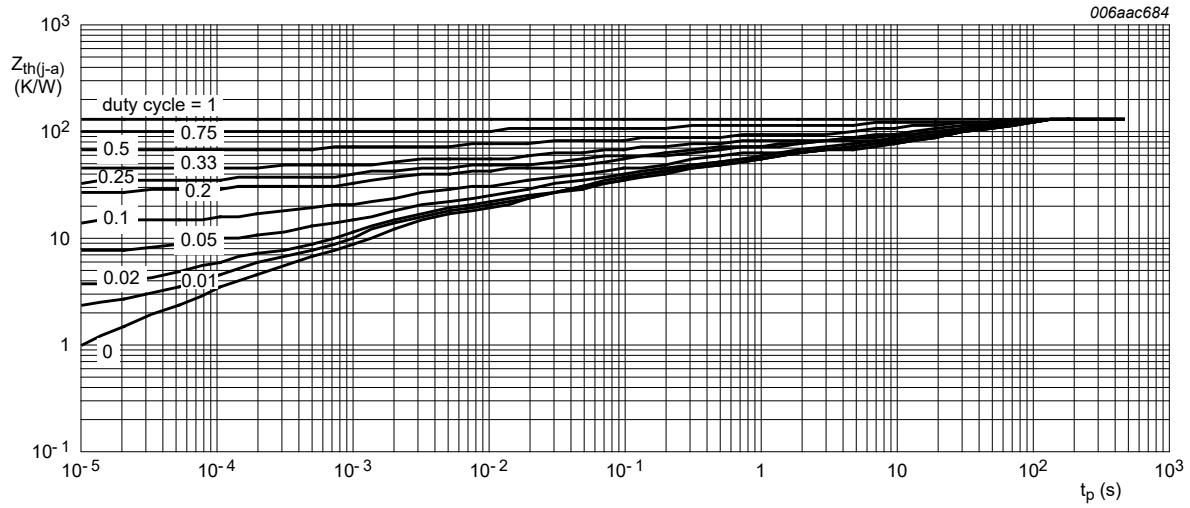
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	298	K/W
			[2]	-	-	151	K/W
			[3]	-	-	114	K/W
			[4]	-	-	154	K/W
			[5]	-	-	76	K/W
$R_{(j-sp)}$	thermal resistance from junction to solder point			-	-	20	K/W

[1] Device mounted on an FR4 PCB; single-sided copper; tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm^2.
[3] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm^2.
[4] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
[5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm^2.



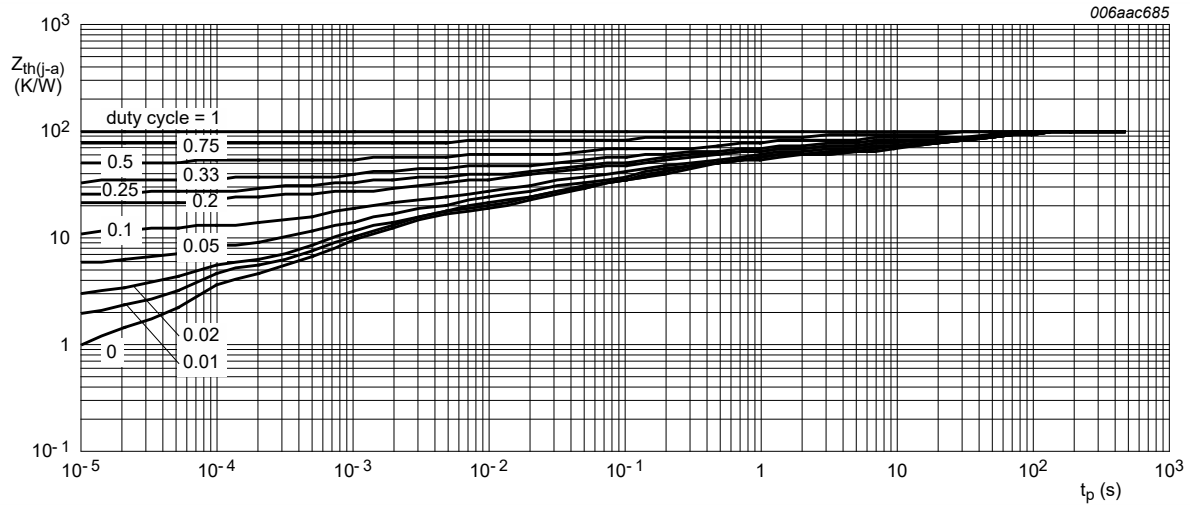
FR4 PCB; single-sided copper; tin-plated and standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



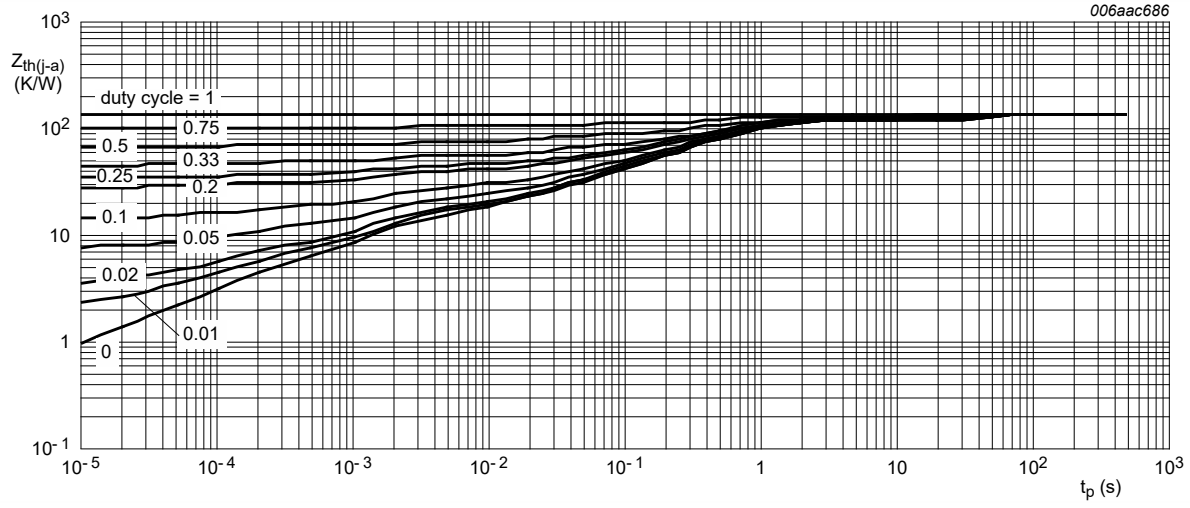
FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm^2

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



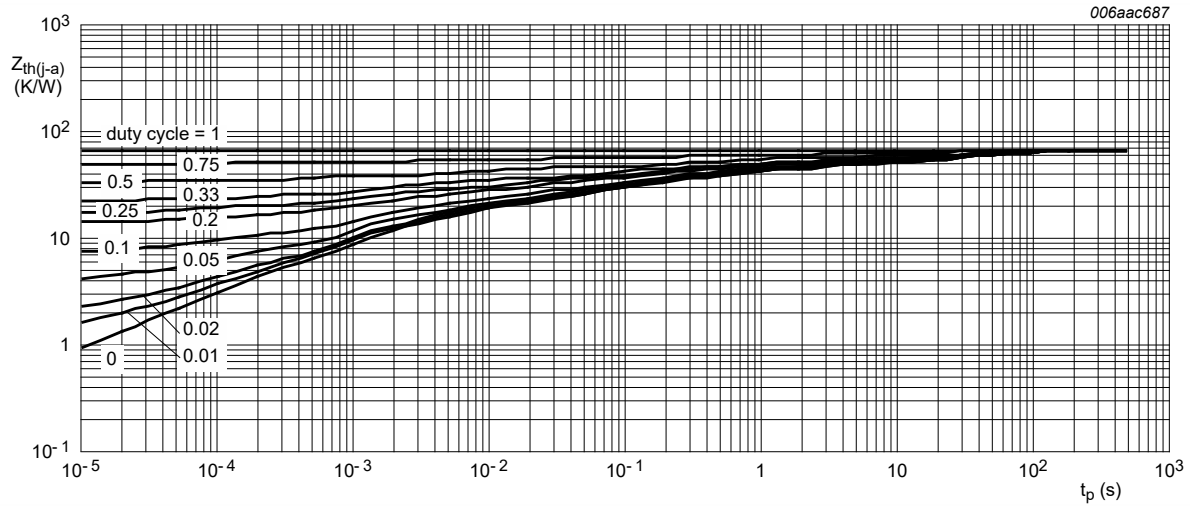
FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm^2

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB; 4-layer copper, standard footprint

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB; 4-layer copper; mounting pad for collector 1 cm^2

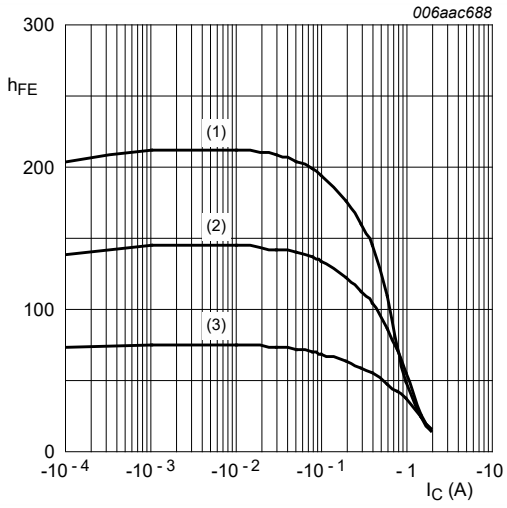
Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

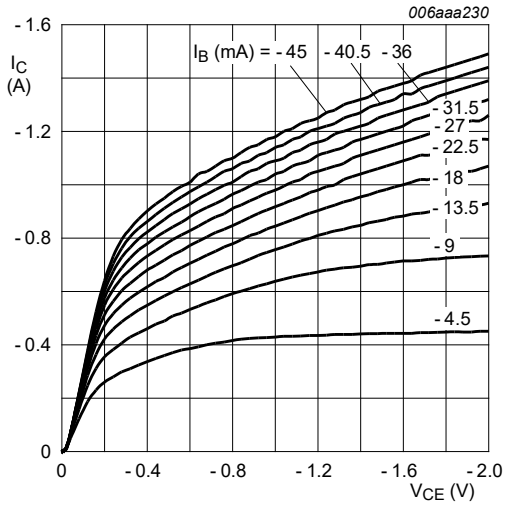
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = -30 V; I_E = 0 A T_{amb} = 25 °C		-	-	-100	nA
		V_{CB} = -30 V; I_E = 0 A; T_j = 150 °C		-	-	-10	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = -5 V; I_C = 0 A T_{amb} = 25 °C		-	-	-100	nA
h_{FE}	DC current gain						
	BC53PA	V_{CE} = -2 V; I_C = -5 mA T_{amb} = 25 °C	[1]	63	-	-	
		V_{CE} = -2 V; I_C = -150 mA T_{amb} = 25 °C		63	-	250	
		V_{CE} = -2 V; I_C = -500 mA T_{amb} = 25 °C		40	-	-	
	BC53-10PA	V_{CE} = -2 V; I_C = -5 mA T_{amb} = 25 °C	[1]	63	-	-	
		V_{CE} = -2 V; I_C = -150 mA T_{amb} = 25 °C		63	-	160	
		V_{CE} = -2 V; I_C = -500 mA T_{amb} = 25 °C		40	-	-	
	BC53-16PA	V_{CE} = -2 V; I_C = -5 mA T_{amb} = 25 °C	[1]	63	-	-	
		V_{CE} = -2 V; I_C = -150 mA T_{amb} = 25 °C		100	-	250	
		V_{CE} = -2 V; I_C = -500 mA T_{amb} = 25 °C		40	-	-	
V_{CEsat}	collector-emitter saturation voltage	I_C = -500 mA; I_B = -50 mA T_{amb} = 25 °C	[1]	-	-	-0.5	V
V_{BE}	base-emitter voltage	V_{CE} = -2 V; I_C = -500 mA T_{amb} = 25 °C	[1]	-	-	-1	V
C_c	collector capacitance	V_{CB} = -10 V; I_E = i_e = 0 A; f = 1 MHz T_{amb} = 25 °C		-	15	-	pF
f_T	transition frequency	V_{CE} = -5 V; I_C = -50 mA; f = 100 MHz T_{amb} = 25 °C		-	145	-	MHz

[1] pulsed; $t_p \leq 300$ µs; $\delta \leq 0.02$



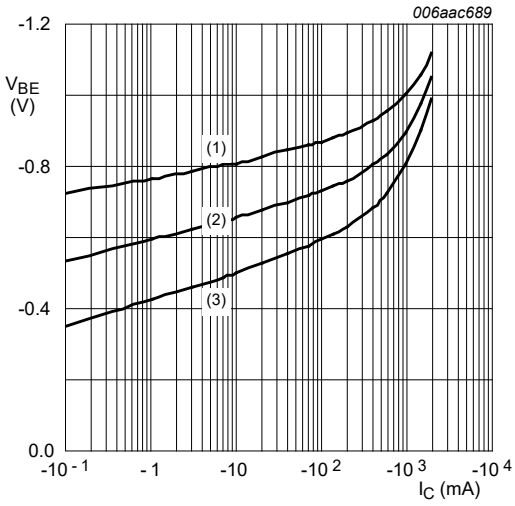
V_{CE} = -2 V
(1) T_{amb} = 100 °C
(2) T_{amb} = 25 °C
(3) T_{amb} = -55 °C

Fig. 7. DC current gain as a function of collector current; typical values



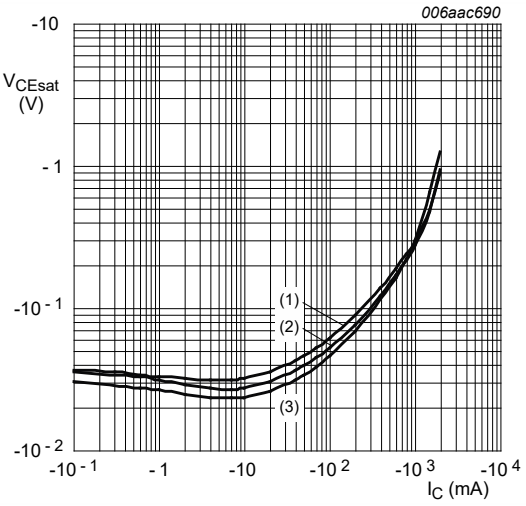
T_{amb} = 25 °C

Fig. 8. Collector current as a function of collector-emitter voltage; typical values



V_{CE} = -2 V
(1) T_{amb} = -55 °C
(2) T_{amb} = 25 °C
(3) T_{amb} = 100 °C

Fig. 9. Base-emitter voltage as a function of collector current; typical values



I_C/I_B = 10
(1) T_{amb} = 100 °C
(2) T_{amb} = 25 °C
(3) T_{amb} = -55 °C

Fig. 10. Collector-emitter saturation voltage as a function of collector current; typical values

11. Test information

11.1. Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

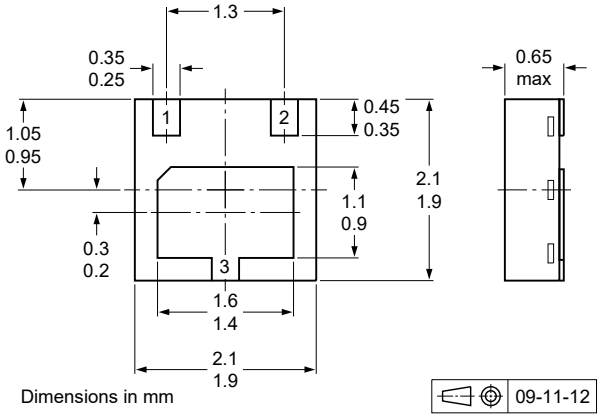


Fig. 11. Package outline SOT1061

13. Soldering

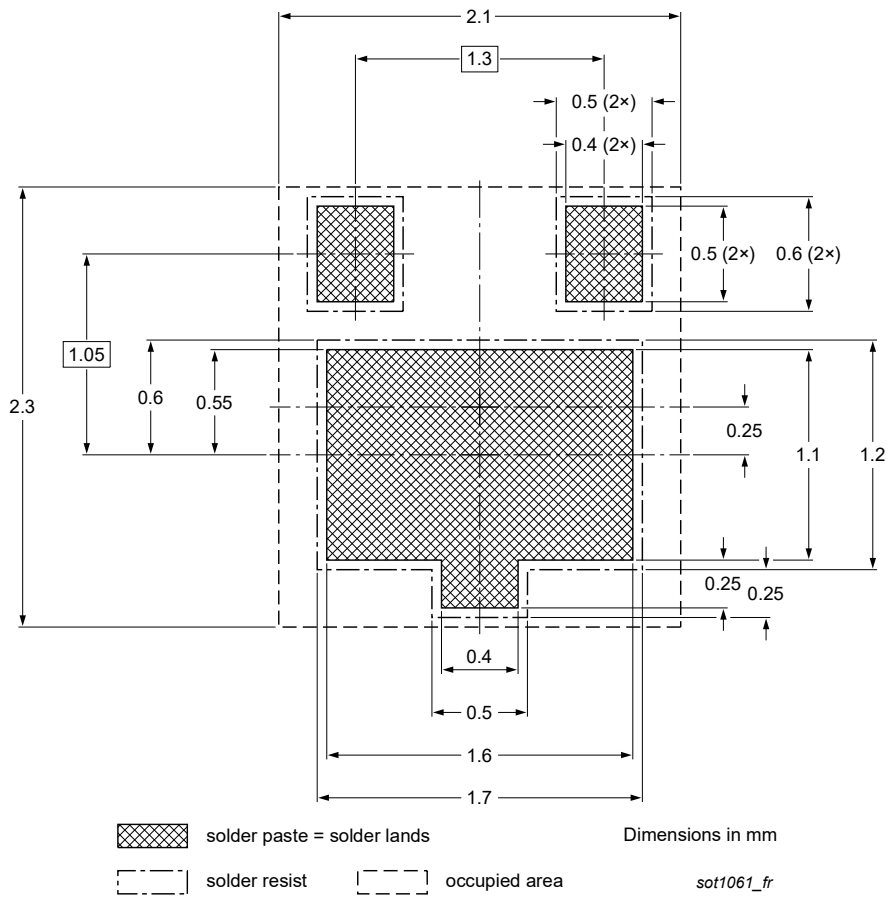


Fig. 12. Reflow soldering footprint for SOT1061

14. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC53PA_SER v.10	20230804	Product data sheet	-	BCP53_BCX53_BC53PA v.9
Modifications:	• Data sheet separated into 3 data sheets • Section "Packing information" removed			
BCP53_BCX53_BC53PA v.9	20220106	Product data sheet	-	BC640_BCP53_BCX53 v.8
BC640_BCP53_BCX53 v.8	20111021	Product data sheet	-	BC640_BCP53_BCX53 v.7
BC640_BCP53_BCX53 v.7	20070604	Product data sheet	-	BC640_BCP53_BCX53 v.6
BC640_BCP53_BCX53 v.6	20050225	Product data sheet	CPCN200405029	BC636_638_640 v.5 BCP51_52_53 v.5 BCX51_52_53 v.4
BC636_638_640 v.5	20011010	Product specification	-	BCX51_52_53 v.5
BCX51_52_53 v.5	20030206	Product specification	-	BCX51_52_53 v.4
BCX51_52_53 v.4	20011010	Product specification	-	BCX54_55_56 v.3

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".
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Contents

1. General description....1
2. Features and benefits....1
3. Applications....1
4. Quick reference data....1
5. Pinning information....2
6. Ordering information....2
7. Marking....2
8. Limiting values....3
9. Thermal characteristics....4
10. Characteristics....7
11. Test information....9
11.1. Quality information....9
12. Package outline....9
13. Soldering....10
14. Revision history....11
15. Legal information....12

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